Introducing
LGA 2011 SOCKET

TE Connectivity's surface mount LGA 2011 socket was designed for use with Intel's Core i7 and Xeon 5 LGA 2011 (Sandy Bridge) CPU processors. The contacts have solder balls for surface mount onto the PCB. A hex ball array provides for a stronger housing and allows for a smaller area for all 2011 balls. The integrated load mechanism (ILM) generates the Z-axis compression load. Robust bolster plate limits PCB bowing during compression.

FEATURES

- Hex ball array gives the housing more strength and provides a smaller area for the contact array
- Available in Gold 15 or Gold 30 contact plating
- Complete socket and hardware system available
- ILM and back plate must be ordered separately

BENEFITS

- Validated to Intel design guides (the validation report is available upon request)

APPLICATIONS

- Servers
- High end desktops

MECHANICAL

- Durability: 30 cycles

MATERIALS

- Socket assembly
  Housing and cap: High temp thermoplastic, UL94V-0
  Contact: Copper alloy, gold plating on contact area over nickel plating
  Solder ball: Sn/Ag/Cu
- ILM: Stainless steel and nickel plated carbon steel
- Dust cover: Thermoplastic, UL94V-0
- Backplate assembly: Steel, nickel plated
- ILM and Backplate Insulators: Adhesive coated polycarbonate film

APPLICATIONS AND SPECIFICATION

- Application specification #114-5474
- Product specification #108-78750
- Instruction sheet #411-78373
- Test report #501-78294

PRODUCT OFFERING

Part Number	Description	Plating
1554653-1	LGA 2011 socket	15 Gold
1-1554653-1	LGA 2011 socket	30 Gold
2134439-1	ILM, Narrow	
1-2134439-1	ILM, Narrow without cover	
2134439-2	ILM, Wide	
1-2134439-2	ILM, Wide without cover	
2134440-1	Back plate	
2-1554653-1	LGA 2011 socket	Pd/Ni

te.com/products/LGA-Sockets

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